

## **UltraPort**<sup>™</sup> **QSFP+**

# QSFP28 with Stamped and Formed Contact Design

Amphenol ICC's UltraPort™ QSFP+ interconnect system comprises of a 38-position, 0.8mm pitch connector built for use in high speed serial applications. Each port offers 4 channels to increase port density which allows more board real estate and cost optimized solutions. The UltraPort™ QSFP+ connector supports next generation 100G+ applications and transmits up to 28Gb/s per channel. It features a stamped and formed contact design providing improved mechanical durability. The resonance dampening features of the design allows superior signal integrity. The design minimizes crosstalk and transmission line impedance discontinuity across the connector interface.

- Electrical interface employs 4 lanes that operates up to 28 Gb/s per channel
- Passive copper and optical solutions
- Stamped and formed contact design provides improved mechanical durability
- The resonance dampening features minimize crosstalk and transmission line impedance discontinuity across the connector interface



#### **FEATURES**

- Electrical interface employs 4 lanes that operate up to 28 Gb/s per channel
- Passive copper and optical solutions
- Stamped and formed contact design
- Resonance dampening features

#### **BENEFITS**

- 100Gb/s aggregated bandwidth solution
- Support various application requirements
- Improved mechanical durability
- Minimizes crosstalk and transmission line impedance discontinuity and provides enhanced signal integrity



#### **TECHNICAL INFORMATION**

#### **MATERIAL**

- Housing: Black color, Glass reinforced, Lead
  Free Solder Reflow Process Compatible Thermo
  Plastic
- Contacts Base Material: Phosphor Bronze
- Plating Solder Tails: Matte tin or Gold flash options
- Plating Mating Area: Gold
- Resonance Dampening Feature: Conductive Polymer

#### **MECHANICAL PERFORMANCE**

- Durability: 250 mating cycles
- Mating Force: 60 N max.
- Contact Normal Force: 0.5 N min./PIN
- PCB Thickness Single Side (Cage): 1.44 mm (0.057in.) min.
- PCB Thickness Belly to Belly (Cage): 2.35 mm (0.093in.) min.
- Unmating Force (Cage): 30 N max.
- Insertion Force to PCB (Cage):
  - 780 N for 1 port
  - 1000 N for 2 Ports
- 1700 N for 4 Ports
- 2400 N for 6 Ports

#### **ELECTRICAL PERFORMANCE**

- Operating Voltage: 30 VDC per contact
- Operating Current: 0.5 A per contact
- Differential Impedance:  $100\Omega + /- 10\Omega$

#### **ENVIRONMENTAL**

- Operating and (Storage) Temperature: -20° to +85° C
- RoHS & Halogen-Free

#### **TOOLING INFORMATION**

- Heat Sinks and Light Pipes: Available
- Configurations:
  - 1XN (N=1,2,3,4,6)
  - 2XN (N=1,2,3)

#### **TARGET MARKETS/APPLICATIONS**



Cellular Infrastructure Network Interface Cards

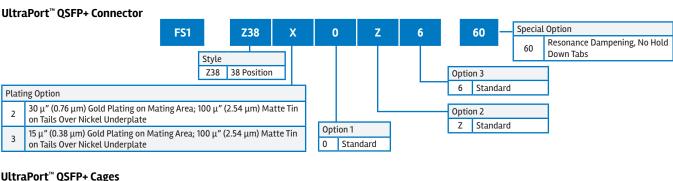


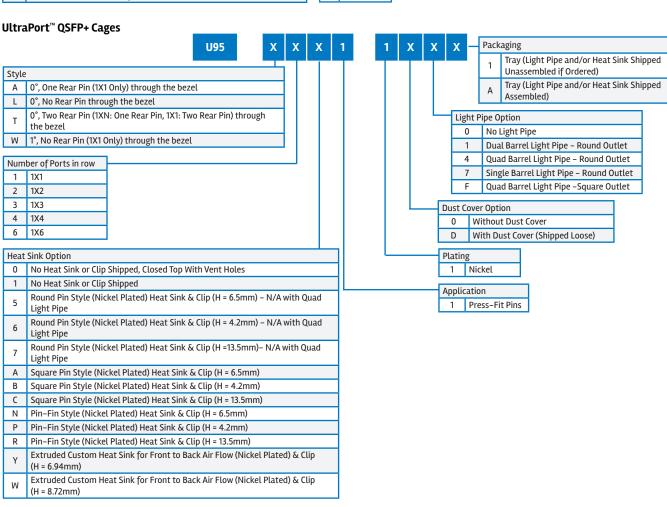
Hubs Switch Servers Storage

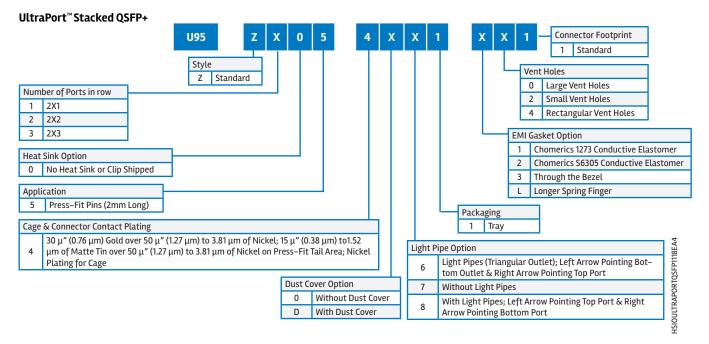


Test and Measurement Equipment

#### UltraPort™ QSFP+







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